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U.S. PTO  
012304

Sir:  
Transmitted herewith for filing is the Patent Application of:

Inventor: **SHIH-WEI CHOU, MING-HSING TSAI, MING-WEI LIN**

For **METHOD TO IMPROVE PLANARITY OF ELECTROPLATED COPPER**

Enclosed are:

- ☒ **2** sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Taiwan Semiconductor Manufacturing Co.**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 770.
TOTAL CLAIMS	39 -20=	19	x 18 =	\$ 342.
INDEP CLAIMS	5 -3=	2	x 86 =	\$ 172.
SUB TOTAL				\$ 1,284.
ASSIGNMENT				\$40.
TOTAL				\$ 1,324.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,324. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR §1.16.
- ☒ Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

**STEPHEN B. ACKERMAN**, REG. NO. 37,761

**EXPRESS MAIL CERTIFICATE**

Express Mail No. **EV385357672US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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